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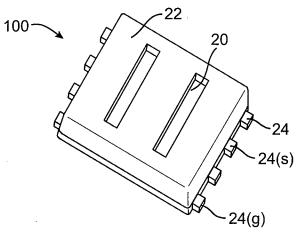


FIG. 1(a)

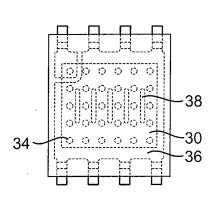


FIG. 1(d)

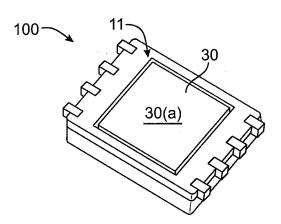


FIG. 1(b)

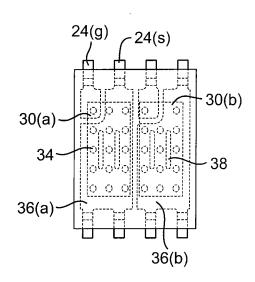
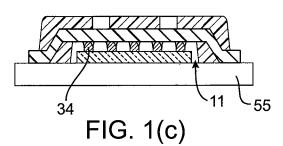
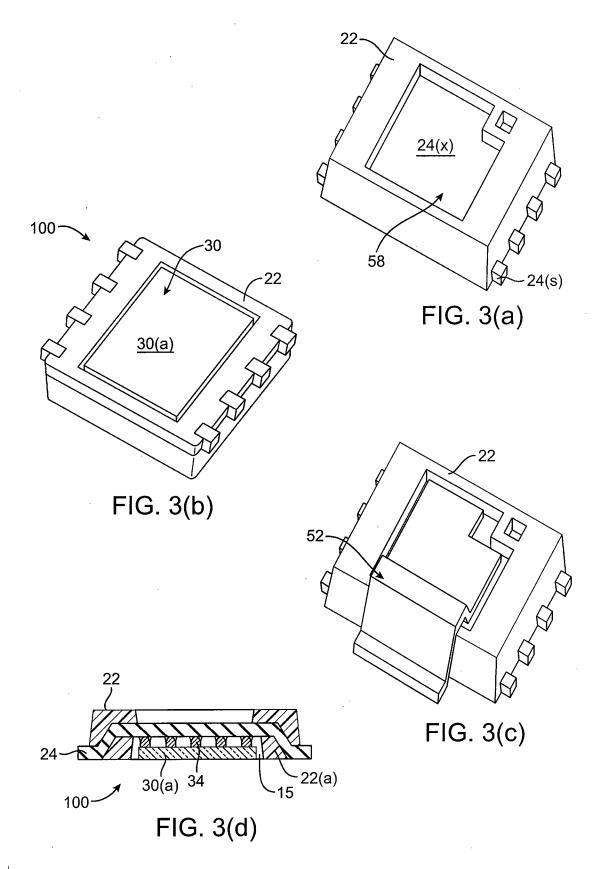


FIG. 2



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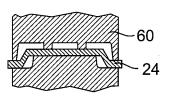


FIG. 4(a)

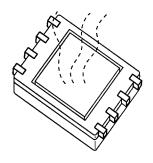


FIG. 4(d)

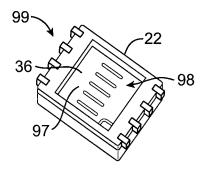


FIG. 4(b)

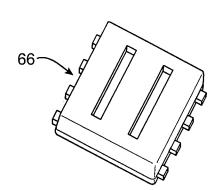


FIG. 4(e)

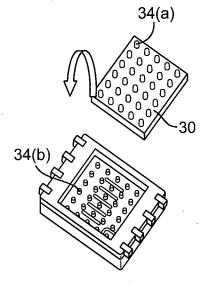


FIG. 4(c)

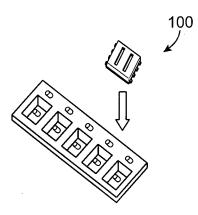
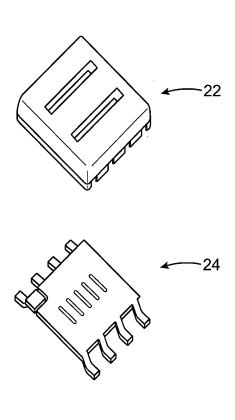
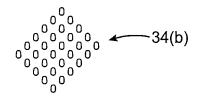


FIG. 4(f)

Patrick R. Jewik, Reg. No. 40,456, (415) 576-0200 Titled: Alternative Flip Chip in Leaded Molded Package Design and Method for Manufacture App. No. 10/772,064 Filed: February 3, 2004 Dckt. No. 018865-012810US Replacement Sheet 4 of 4

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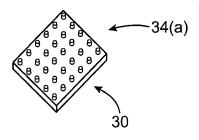


FIG. 5

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